AMENDMENTS TO THE SPECIFICATION

IN THE SPECIFICATION:

Please replace the paragraph beginning on page 8, line 2, with the following rewritten paragraph:

A space formed under the movable block 24 is ~~communicated to~~ in communication with an air path 28 of the fixed block 26 when the work piece 30 is clamped between the upper and lower dies 20 and 22, so that an air path for air suction can be formed. A notch 24b is formed in a side face of the movable block 24. The notch 24b acts as an air path for air suction. The air path 28 is ~~communicated to~~ in communication with a vacuum unit 70, which is located outside of the press section "A", via tubes and an open-close valve.

Please replace the paragraph beginning on page 9, line 18, with the following rewritten paragraph:

After the parting face of the upper die 20 is covered with the release film 50, the molding die is closed to clamp the work pieces 30 by the upper die 20 and the lower die 22 together with the release film 50. By clamping the work piece 30 between the upper die 20 and the lower die 22, the semiconductor chip 32 is accommodated in the concave section ~~32~~ 23 of the upper die 20; the movable block 24 of the lower die 22 is moved downward, and the substrate 31 is accommodated in the lower die 22.

Please replace the paragraph beginning on page 10, line 11, with the following rewritten paragraph:

The specific areas including the work pieces 30 are enclosed and air-tightly sealed with the release film 50. In this state, the vacuum unit 70 is driven so as to compulsorily discharge air from the pots 40, the resin paths 46 and the connecting portions of the work pieces 30 via the air path 28. Fig. 3 shows the state of discharging air from the pots 40, the resin paths 46 and the connecting portions of the work pieces ~~32~~ 30. The air is discharged outside via a space between the movable block 24 and an inner face of a block hole, in which the movable block 24 is provided, and the air vent 48.